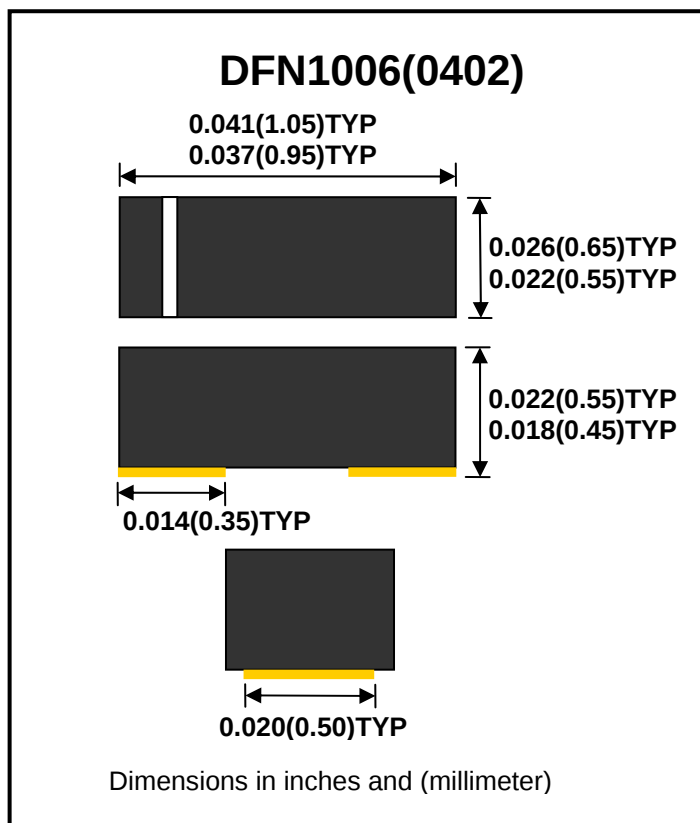


**CDB0130QRL****100mA 30V****FEATURES**

- Low forward voltage
- Thin & leadless package for space saving

MECHANICAL CHARACTERISTICS

- Case: DFN1006(0402) mold package
- Terminal: Gold plated, solderable per
MIL-STD-750, method 2026
- Marking: cathode band & BP
- Weight: 0.001 gram(approx.)

**Maxim Rating And ELECTRICAL CHARACTERISTICS (at TA=25°C unless otherwise noted)**

Parameter	Condition	Symbol	Min	Typ	Max	Unit
Repetitive peak reverse voltage		VRRM			35	V
Reverse voltage		VR			30	V
Average forward current		Io			100	mA
Forward current surge peak	8.3 ms single half sine-wave superimposed on rate load (JEDEC method)	IFSM			1	A
Storage/Operation temperature		T _{Sgt}	-40		125	°C
Junction temperature		T _J			125	°C
Forward voltage	IF=10mA IF=20mA	VF			0.29 0.30	V
Reverse current	VR=30V	IR			30	uA



Typical Characteristics

Fig.1-forward characteristics

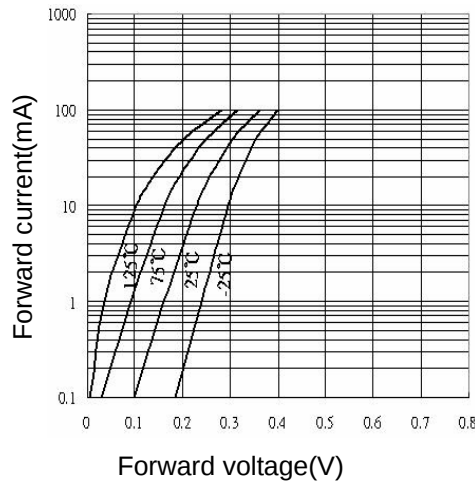


Fig.2-Reverse characteristics

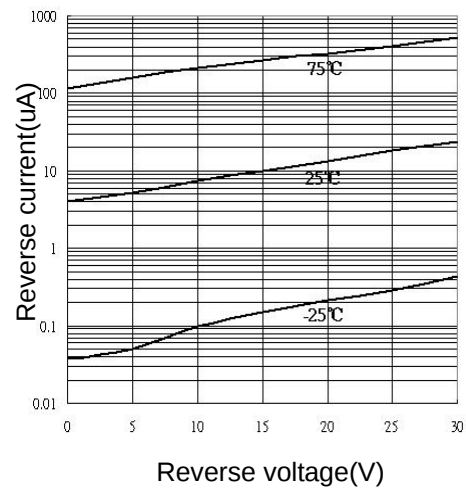


Fig.3 - Capacitance between terminals characteristics

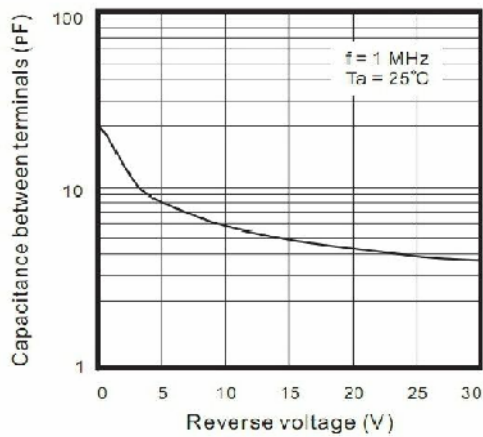


Fig.4 - Current derating curve

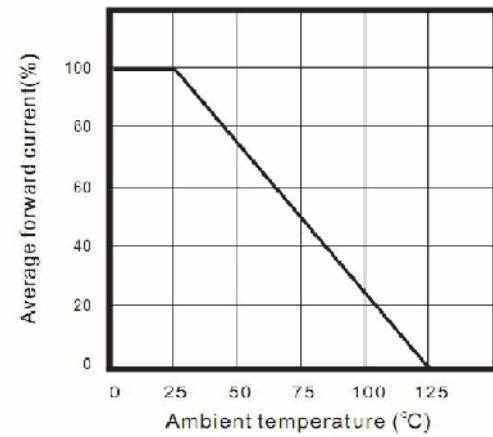


Fig. 5 - VF Dispersion map

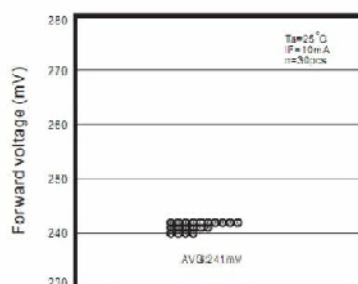


Fig. 6 - IR Dispersion map

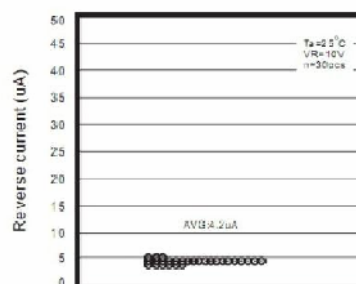
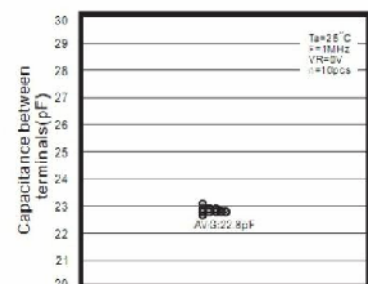
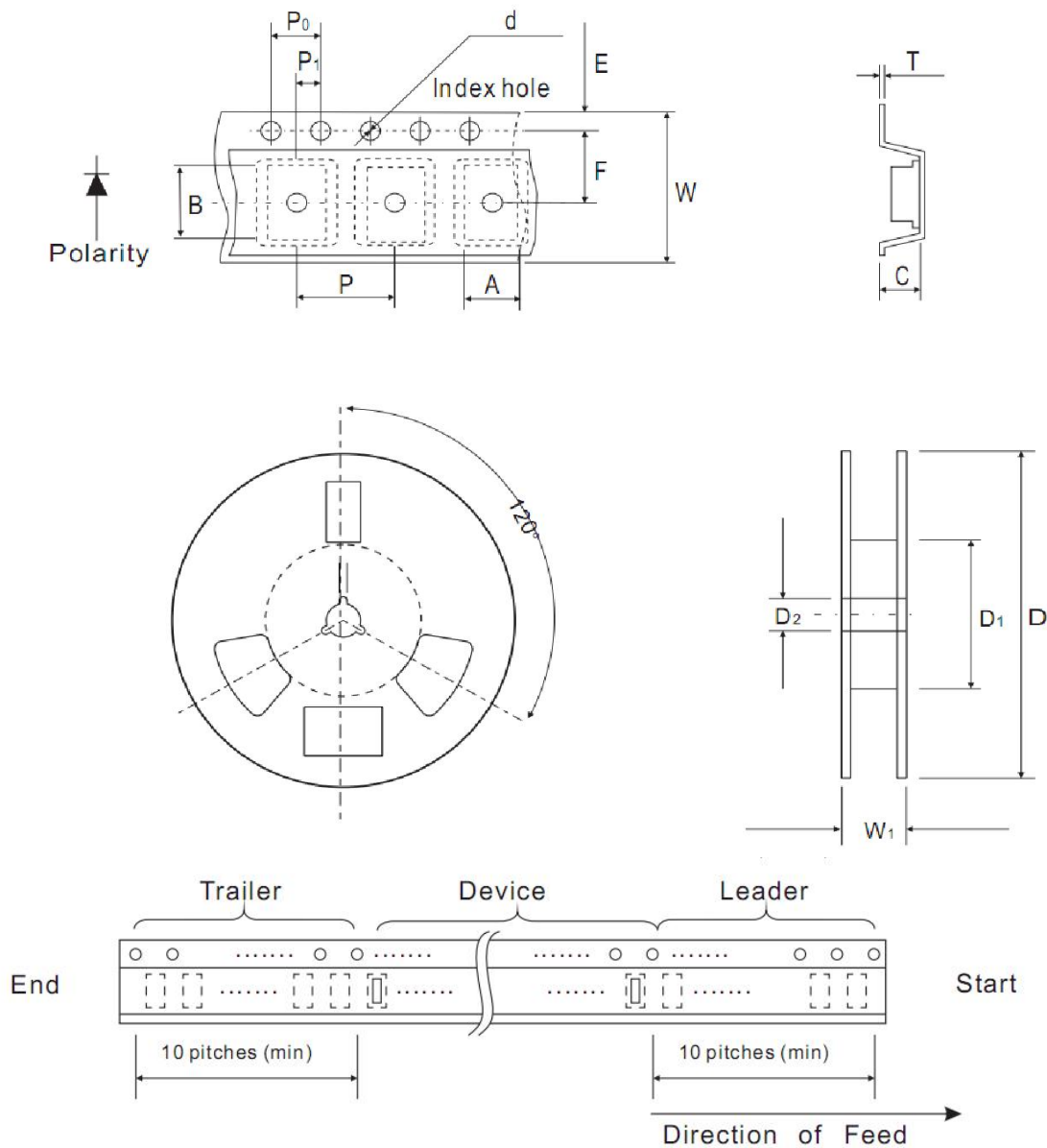


Fig. 7 - CT Dispersion map





Packing Specification



Tape & Reel Dimensions

Package	Unit	A	B	C	d	D	D1	D2
DFN1006	mm	0.67±0.10	1.12±0.10	0.60±0.10	1.50±0.10	178±1	60MIN	13.0±0.20
	inch	0.026±0.004	0.044±0.004	0.024±0.004	0.060±0.004	7.008±0.04	2.362MIN	0.512±0.008

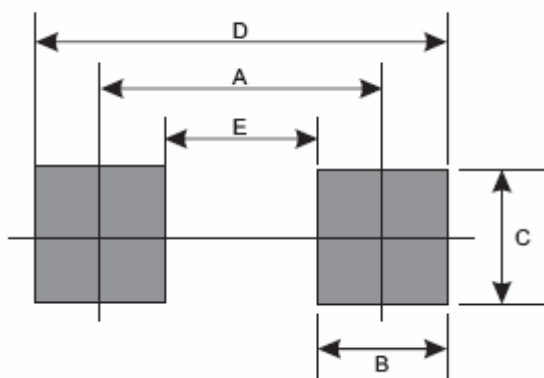
package	Unit	E	F	P	P0	P1	T	W	W1
DFN1006	mm	1.75±0.10	3.5±0.10	4.0±0.10	4.0±0.10	2.0±0.10	0.22±0.03	8.0±0.10	13.5MAX
	inch	0.069±0.004	0.138±0.004	0.157±0.004	0.157±0.004	0.079±0.004	0.009±0.002	0.315±0.004	0.531MAX



Standard Package

Package	Reel Size	Qty/Reel
DFN1006	7"	5000 pcs

RECOMMENDED SOLDERING FOOTPRINT



Reflow Soldering

Product Size	Dimension/ mm				
	A	B	C	D	E
DFN1006	0.750	0.500	0.700	1.250	0.250
	0.030"	0.020"	0.028"	0.049"	0.010"

Marking Code

Part Number	Marking Code
CDB0130QRL	BP



DISCLAIMERS

These products are not designed for use in applications where any failure or malfunction may result in personal injury, death or severe property or environmental damage such as medical, military, aircraft, space or life support equipments.